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FIG. 3A

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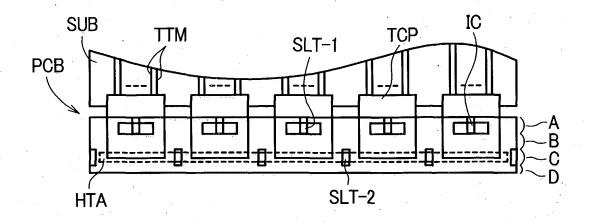
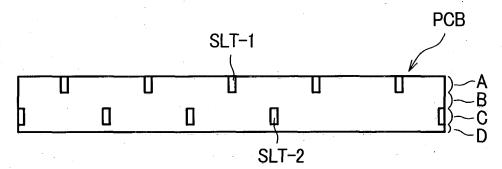


FIG. 3B

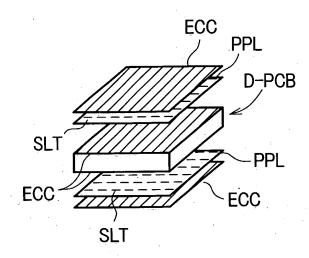


TAKENAKA HITA.0417 Page 4 of 8 SLT PPL PP D-PCB (P-4B) SLT ECC (P-3B) (P-6B)FIG. 5 (P-2B) PPL (P-1B) ECC ECC RGN (P-5B)

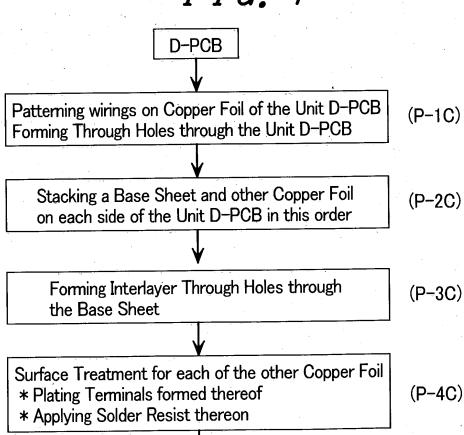
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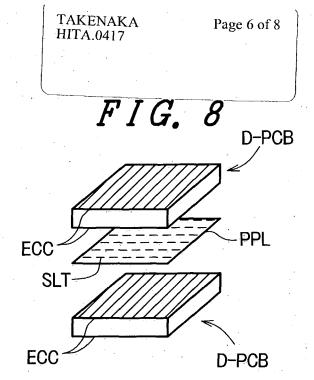
## FIG. 6

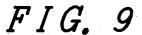


## F I G. 7



Completion of Multilayer Printed Circuit Board Q-PCB and then Components are mounted thereon





Copper Foil of a pair of the Units I

(P-1D)

(P-2D)

(P-3D)

(P-4D)

Patterning wirings on each Copper Foil of a pair of the Units D-PCB Forming Through Holes through respective one of the Unit D-PCB

Stacking the pair of the Units D-PCB with each other inter laminating a Base Sheet therebetween

Forming Interlayer Through Holes throughout the Laminate

Surface Treatment for Copper Foil at both sides of the Laminate

- \* Plating Terminals formed of the Copper Foil
- \* Applying Solder Resist on the Copper Foil

Completion of Multilayer Printed Circuit Board LQ-PCB and then Components are mounted thereon

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FIG 10A

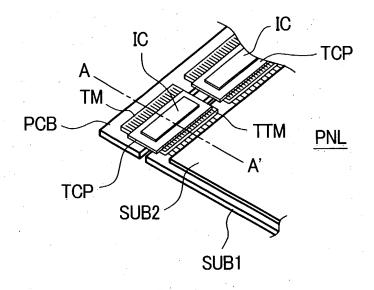
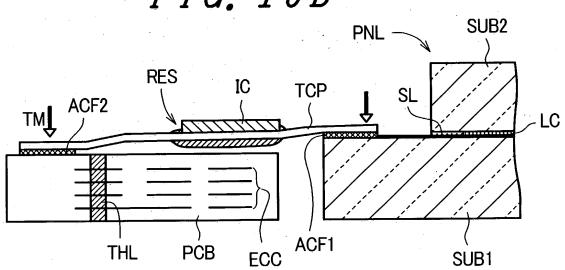


FIG. 10B



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F I G. 11

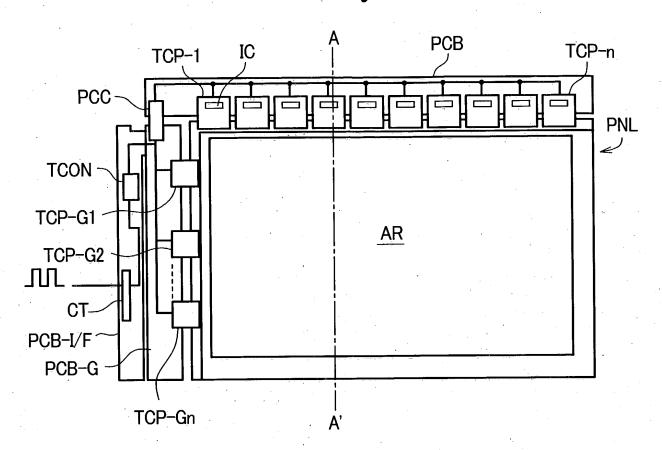


FIG. 12

